

## Electronic Patent Application Fee Transmittal

Application Number:	10611334
Filing Date:	30-Jun-2003
Title of Invention:	MEMS PACKAGING USING A NON-SILICON SUBSTRATE FOR ENCAPSULATION AND INTERCONNECTION
First Named Inventor/Applicant Name:	John Heck
Filer:	Kevin Reif/cathy dikes
Attorney Docket Number:	42P16325

Filed as Large Entity

### **Utility Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1740</b>